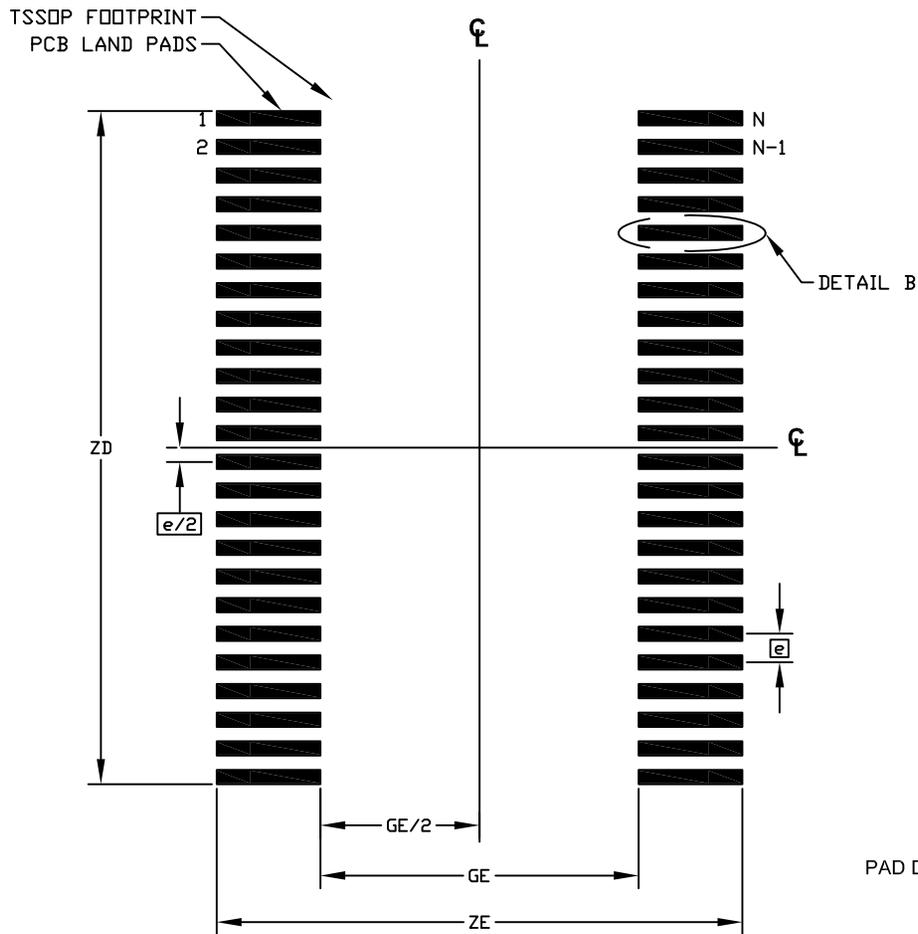
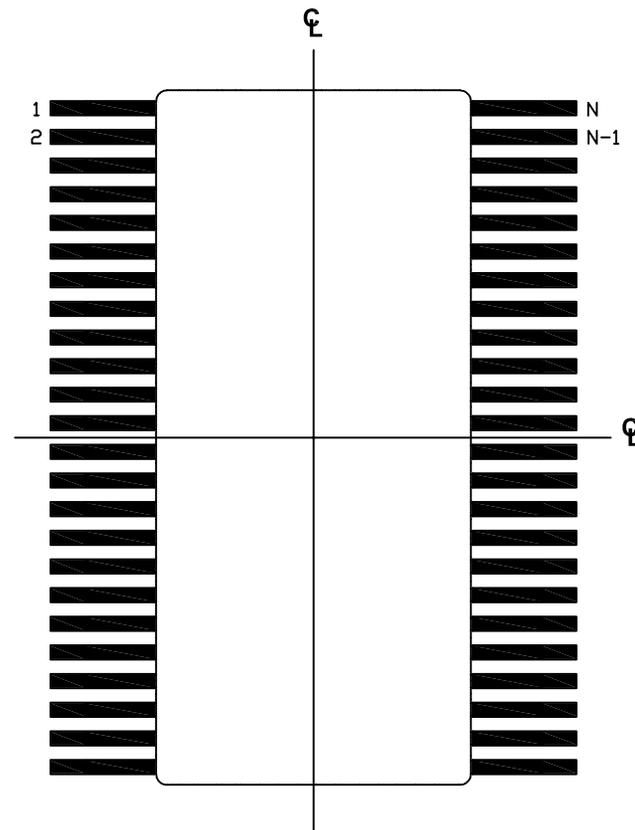


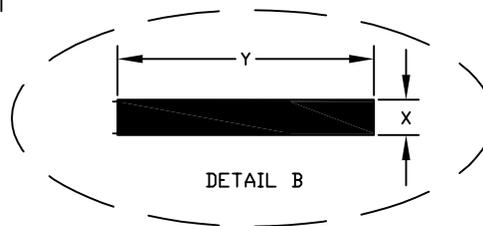
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAIL INFORMATION



| DIM | MILLIMETERS |          |     | INCHES |          |     |
|-----|-------------|----------|-----|--------|----------|-----|
|     | MIN         | NOM      | MAX | MIN    | NOM      | MAX |
| e   |             | 0.40 BSC |     |        | .016 BSC |     |
| GE  |             | 4.45 REF |     |        | .175 REF |     |
| N   |             | 48 PINS  |     |        | 48 PINS  |     |
| X   |             | 0.20 TYP |     |        | .008 TYP |     |
| Y   |             | 1.45 TYP |     |        | .057 TYP |     |
| ZD  |             | 9.40 REF |     |        | .370 REF |     |
| ZE  |             | 7.35 REF |     |        | .289 REF |     |

NOTES:

1. REFERENCE PKG. OUTLINE: 21-1077
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
4. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maximintegrated.com/support> for further questions.

TITLE:  
PACKAGE LAND PATTERN,  
[U48+2] TSSOP

APPROVAL

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